

Features

- Uses CRM(CQ) advanced SkyMOS2 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g \times R_{DS(on)}$ product(FOM)
- AEC-Q101 Qualified

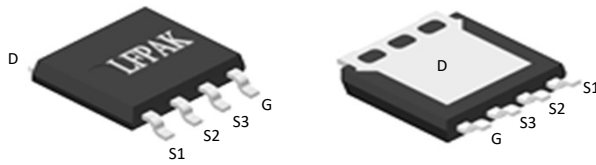
Product Summary

V_{DS}	40V
$R_{DS(on).typ}$	5mΩ
I_D	70A

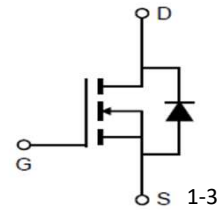
Applications

- Motor control and drive
- Battery management System
- UPS (Uninterruptible Power Supplies)

100% DVDS Tested
100% Avalanche Tested



CRSY052N04N2Z



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRSY052N04N2Z	052N04N2Z	LPAK5x6	Tape&reel	N/A	N/A	4000pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	40	V
Continuous drain current $T_C = 25^\circ\text{C}$ (Silicon limit) $T_C = 100^\circ\text{C}$ (Silicon limit)	I_D	70 50	A
Pulsed drain current ($T_C = 25^\circ\text{C}$, t_p limited by T_{jmax})	$I_{D \text{ pulse}}$	280	A
Avalanche energy, single pulse ($I_{AS} = 21\text{A}$, $R_g = 50\Omega$) ^[1]	E_{AS}	66	mJ
Gate-Source voltage	V_{GS}	± 20	V
Power dissipation ($T_C = 25^\circ\text{C}$)	P_{tot}	58	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+175	$^\circ\text{C}$
Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s)	T_{sold}	260	$^\circ\text{C}$

※. Notes:

EAS is tested at starting $T_j = 25^\circ\text{C}$, $L = 0.3\text{mH}$, $I_{AS} = 21\text{A}$, $V_{GS} = 10\text{V}$.

Thermal Resistance

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case (junction-heat spreader)	R_{thJC}	2.6	°C/W
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	52	

Electrical Characteristic (at $T_j = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV_{DSS}	40	-	-	V	$V_{GS}=0V, I_D=250\mu A$
		40	-	-	V	$V_{GS}=0V, I_D=1mA$
Gate threshold voltage	$V_{GS(th)}$	2.0	3.0	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	I_{DSS}	-	-	1 100	μA	$V_{DS}=40V, V_{GS}=0V$ $T_j=25^\circ C$ $T_j=125^\circ C$
Gate-source leakage current	I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	5.0	6.3	mΩ	$V_{GS}=10V, I_D=40A$ $T_j=25^\circ C$
Transconductance	g_{fs}	-	82	-	S	$V_{DS}=5V, I_D=40A$

Dynamic Characteristic

Input Capacitance	C_{iss}	-	1190	-	pF	$V_{GS}=0V, V_{DS}=20V, f=1MHz$
Output Capacitance	C_{oss}	-	400	-		
Reverse Transfer Capacitance	C_{rss}	-	20	-		
Gate Total Charge	Q_G	-	18	-	nC	$V_{GS}=10V, V_{DS}=20V,$ $I_D=40A, f=1MHz$
Gate-Source charge	Q_{gs}	-	8	-		
Gate-Drain charge	Q_{gd}	-	2	-		
Turn-on delay time	$t_{d(on)}$	-	11	-	ns	$V_{GS}=10V, V_{DD}=20V,$ $R_{G_ext}=3\Omega, I_D=40A$
Rise time	t_r	-	23	-		
Turn-off delay time	$t_{d(off)}$	-	12	-		
Fall time	t_f	-	6	-		
Gate resistance	R_G	-	1.2	-	Ω	$V_{GS}=0V, V_{DS}=0V, f=1MHz$

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Diode continuous forward current	I_S	-	-	70	A	$T_C = 25^{\circ}\text{C}$
Diode pulse current	I_S pulse	-	-	280	A	$T_C = 25^{\circ}\text{C}$
Body Diode Forward Voltage	V_{SD}	-	0.9	1.4	V	$V_{GS}=0V, I_{SD}=40A$
Body Diode Reverse Recovery Time	t_{rr}	-	20	-	ns	$I_F=40A, dI/dt=100A/\mu s$
Body Diode Reverse Recovery Charge	Q_{rr}	-	6	-	nC	

Typical Performance Characteristics

Fig 1: Output Characteristics

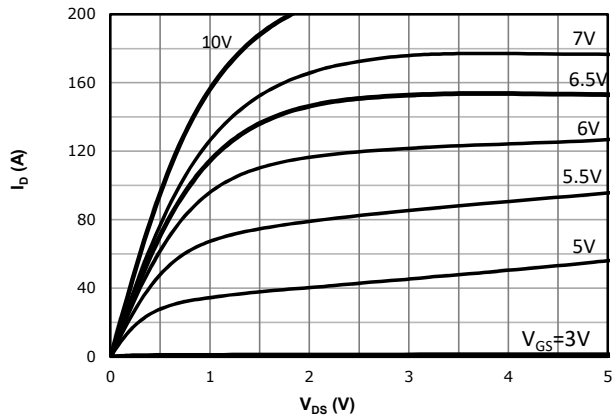


Fig 2: Transfer Characteristics

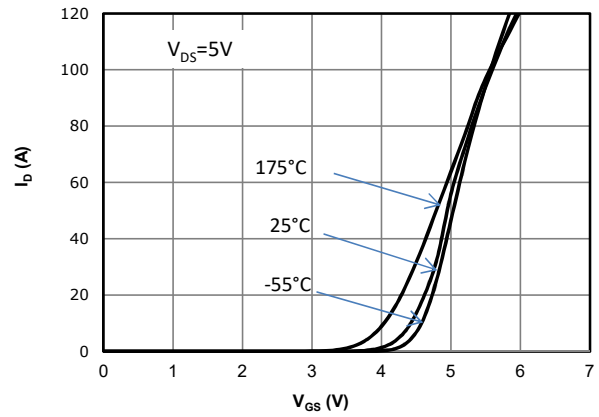


Fig 3: Rds(on) vs Drain Current and Gate Voltage

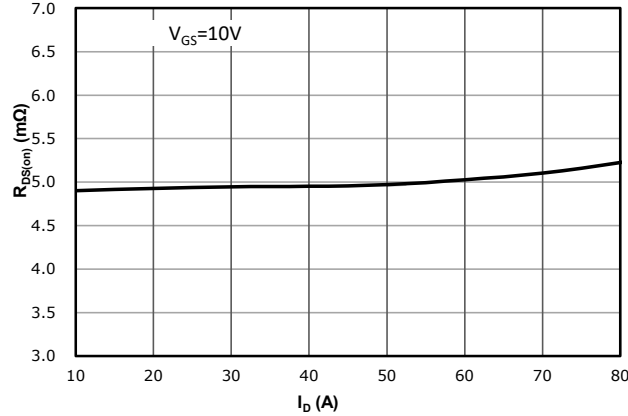


Fig 4: Rds(on) vs Gate Voltage

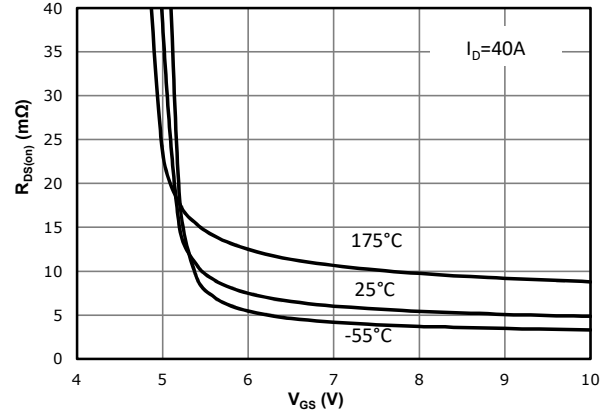


Fig 5: Rds(on) vs. Temperature

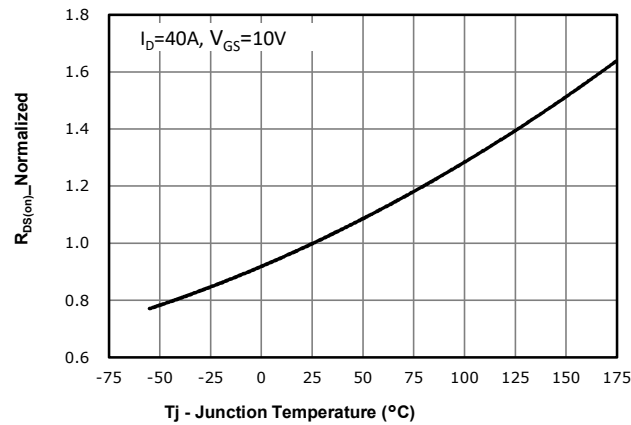


Fig 6: Vgs(th) vs. Temperature

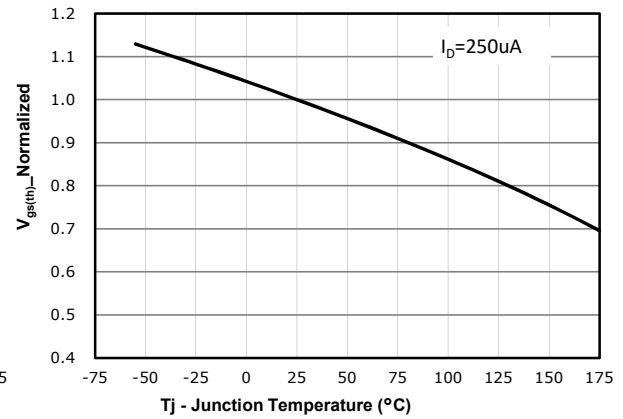


Fig 7: BVdss vs. Temperature

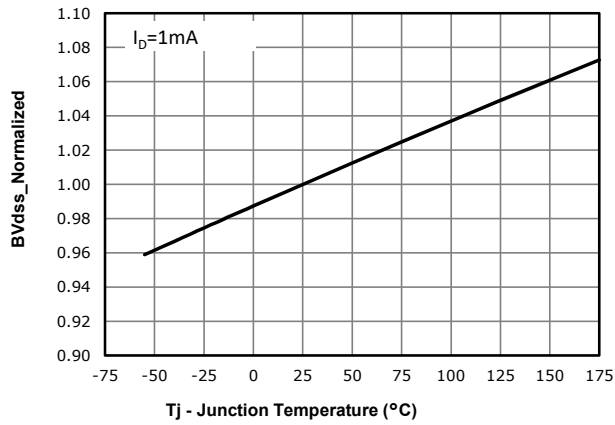


Fig 8: Capacitance Characteristics

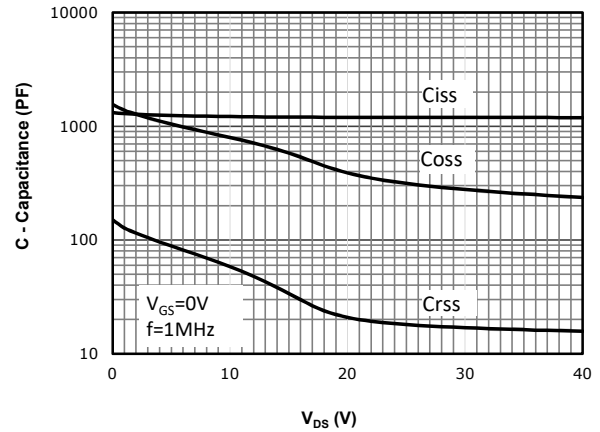


Fig 9: Gate Charge Characteristics

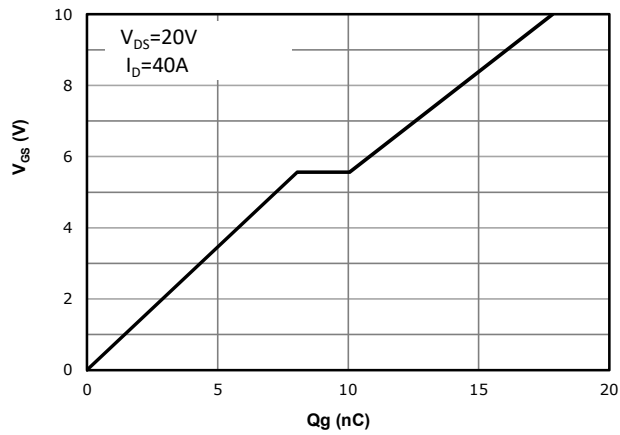


Fig 10: Body-diode Forward Characteristics

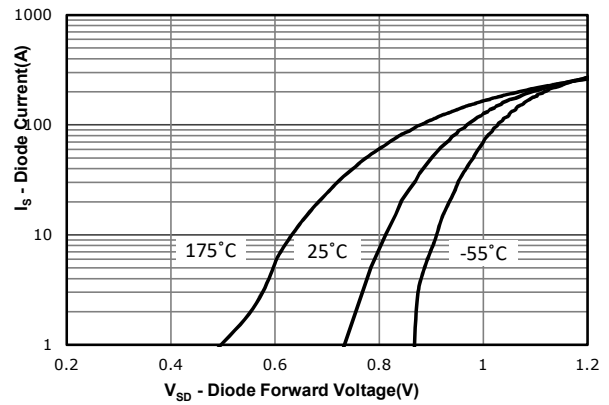


Fig 11: Power Dissipation

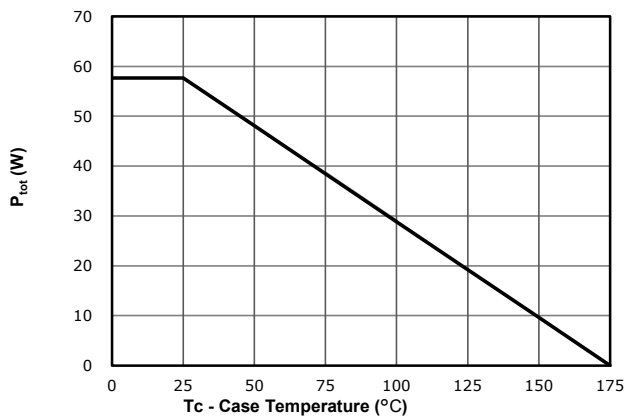


Fig 12: Drain Current Derating

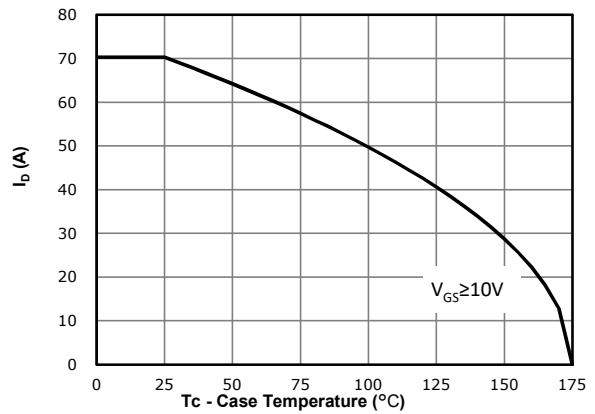


Fig 13: Safe Operating Area

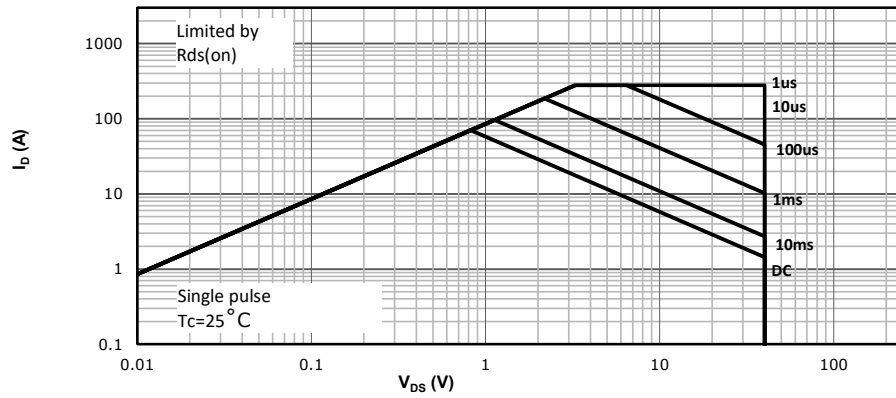
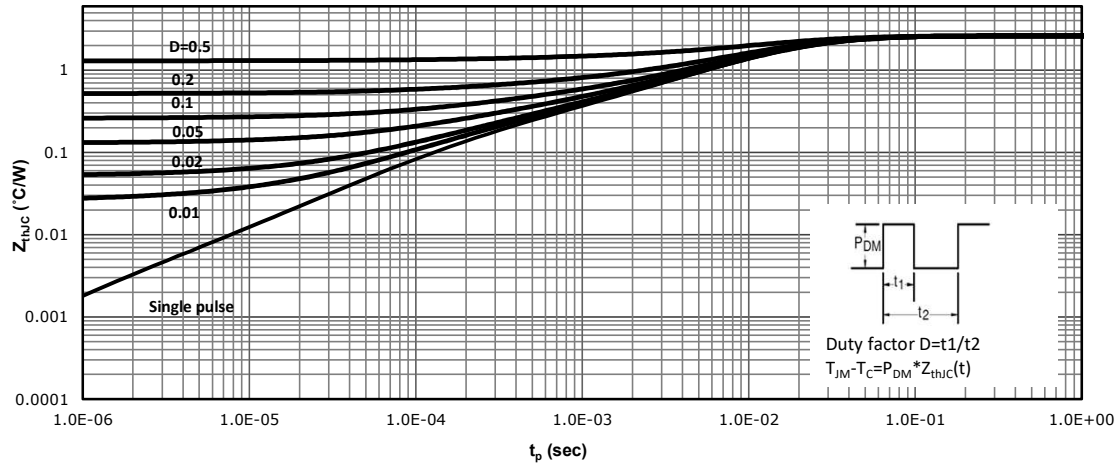
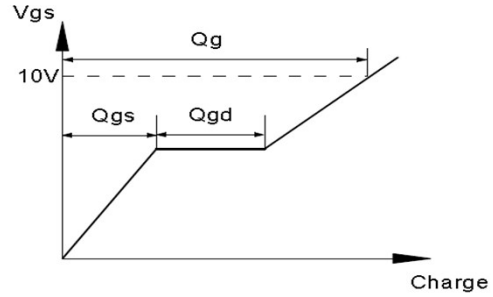
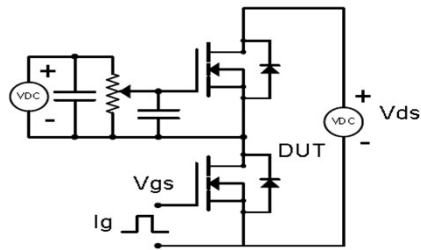


Fig 14: Max. Transient Thermal Impedance

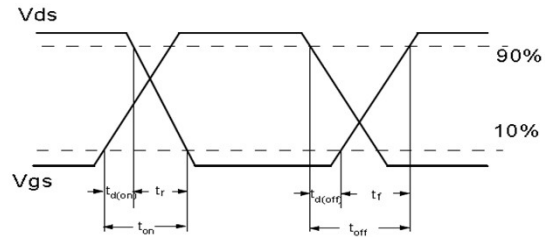
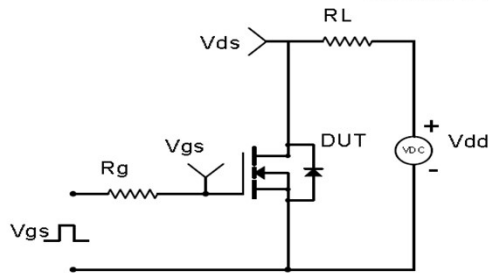


Test Circuit & Waveform

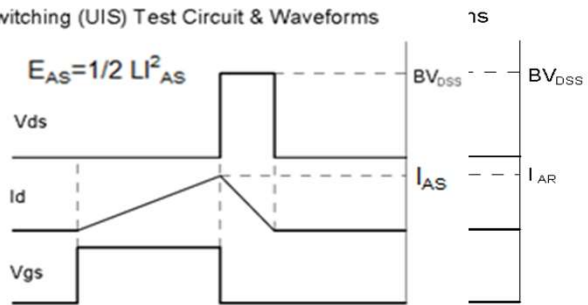
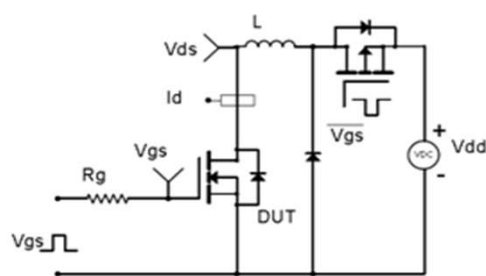
Gate Charge Test Circuit & Waveform



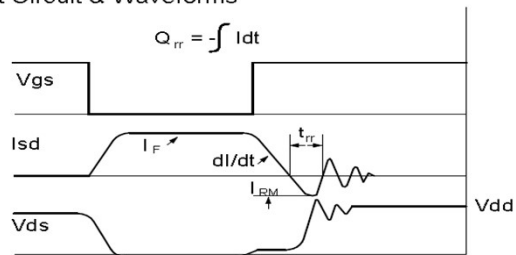
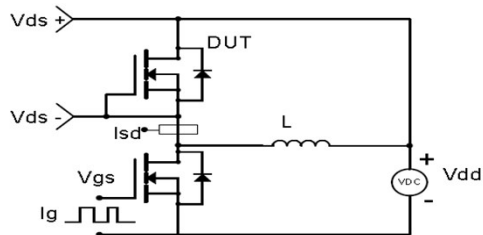
Resistive Switching Test Circuit & Waveforms



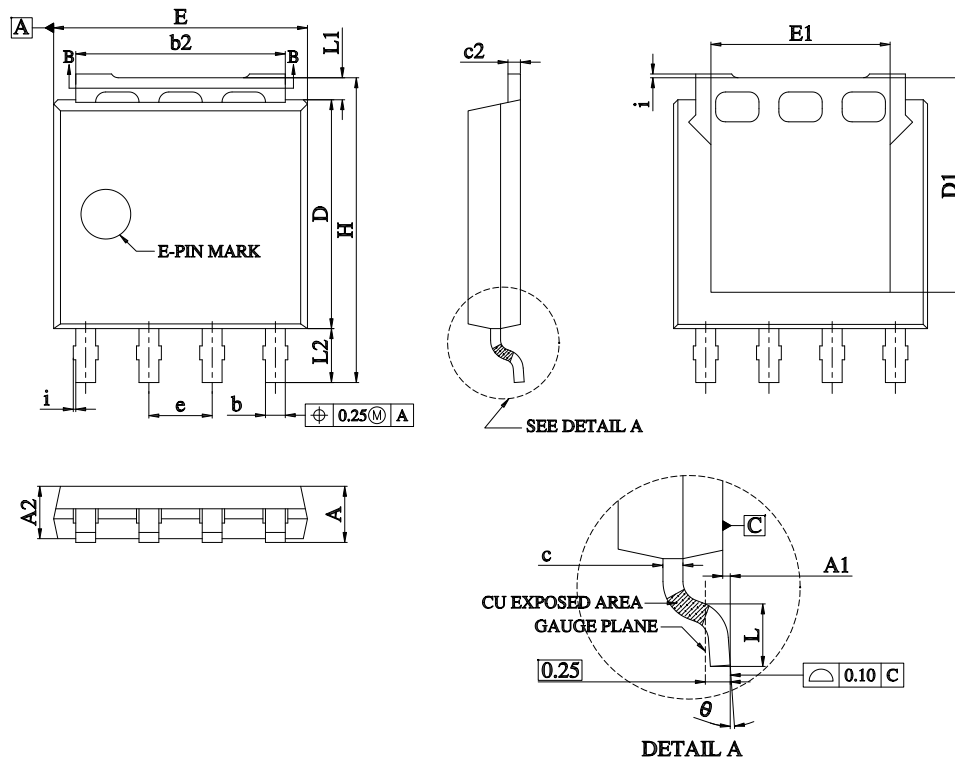
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



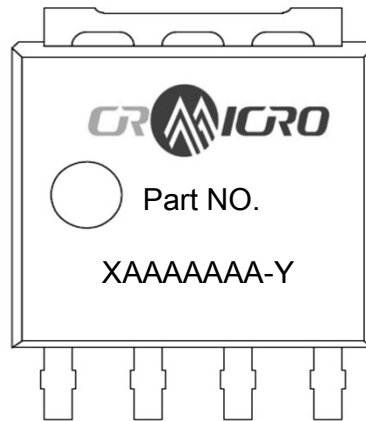
Diode Recovery Test Circuit & Waveforms



Package Outline: LPAK5x6



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.00	1.20	0.039	0.047
A1	0.00	0.15	0.000	0.006
A2	0.95	1.15	0.037	0.045
b	0.32	0.50	0.013	0.020
b2	3.80	4.41	0.150	0.174
c	0.17	0.25	0.007	0.010
c2	0.22	0.30	0.009	0.012
D	4.45	4.70	0.175	0.185
D1	--	4.45	--	0.175
E	4.90	5.30	0.193	0.209
E1	3.45	3.75	0.136	0.148
e	1.27 BSC		0.050 BSC	
H	5.95	6.25	0.234	0.246
i	--	0.25	--	0.010
L	0.40	0.85	0.016	0.033
L1	0.27	0.57	0.011	0.022
L2	0.80	1.30	0.031	0.051
θ	0°	8°	0°	8°

Marking**NOTE:**

XAAAAAAAA-Y

X

—Assembly location code

AAAAAAA

—Assembly lot NO. last 7digits

Y

—Bin code

Revision History

Revision	Date	Major changes
1.0	2023/8/30	Release of preliminary version.
2.0	2025/3/7	1.Update Package name; 2.Delete Dynamic Characteristic parameters spec. 3.Update Fig5/Fig12/Id/Is/ Is pulse.

Disclaimer

CRM reserves the right to change any product or information in this Specification at any time without prior notice.

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